## **KBJ6005 THRU KBJ610**

# **Glass Passivated Single-Phase Bridge Rectifier**

Reverse Voltage 50 to 1000 V

Forward Current 4 A

KBJ

#### **Features**

- · Glass passivated chip junction
- · Ideal for printed circuit board
- Plastic material has Underwriters Laboratory Flammability Classification 94V-0
- Reliable low cost construction utilizing molded plastic technique

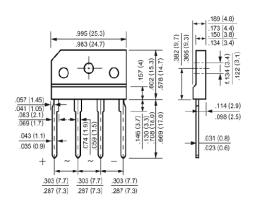
#### **Mechanical Data**

· Case: Molded plastic, KBJ

• Epoxy: UL94V- 0 rate flame retardant

• Terminals:Leads solderable per MIL-STD-202,

Method 208 guaranteed • Mounting Position: Any



Dimensions in inches and (millimeters)

### **Maximum Ratings and Electrical Characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate by 20%.

Parameter	Symbols	KBJ6005	KBJ601	KBJ602	KBJ604	KBJ606	KBJ608	KBJ610	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Average Rectified Rectified Current at T <sub>C</sub> = 110 °C	I <sub>F(AV)</sub>	6							Α
Non-repetitive Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	150							А
Maximum Forward Voltage at 3 A DC	V <sub>F</sub>	1						V	
$ \begin{array}{ll} \mbox{Maximum Reverse Current} & T_{\mbox{\scriptsize A}} = 25 \ ^{\circ}\mbox{\scriptsize C} \\ \mbox{at Rated DC Blocking Voltage} & T_{\mbox{\scriptsize A}} = 125 \ ^{\circ}\mbox{\scriptsize C} \\ \end{array} $	I <sub>R</sub>	5 500							μA
Typical Junction Capacitance 1)	C <sub>j</sub>	80							pF
Typical Thermal Resistance 2)	$R_{\theta JC}$	1.5							°C/W
Operating Junction Temperature Range	T <sub>j</sub>	- 55 to + 150							°C
Storage Temperature Range	T <sub>stg</sub>	- 55 to + 150							°C

<sup>1)</sup> Measured at 1 MHz and applied reverse voltage of 4 V DC

<sup>&</sup>lt;sup>2)</sup> Thermal Resistance from Junction to Case with Device Mounted on 75 mm X 75 mm X 1.6 mmCu Plate Heatsink.





